

QF3129M

No Clean Liquid Flux



Product Description

QF3129M is a newly formulated RA flux suitable for both tin/lead and lead free applications. This flux has been formulated such that no solder balls are formed and bridging problems are minimised.

Application

QF3129M is specially formulated for foaming and dipping process. Recommended onboard preheat temperature is about 80 - 100 °C. This flux is compatible with both SnPb and Lead Free solders.

Residue Removal

Since the residues are minimal and non-corrosive, removal is usually not required. If cleaning is required, the flux residue could be removed by any solvent or aqueous flux cleaner available in the market.

Recommended Solvent

Asahi's complementary Solvent #2000. Solvent can be stored for about 2 years under normal storage conditions of 25°C.

Health and Safety

Observe standard precautions for handling and use, such as well-ventilated areas and avoidance of prolonged or repeated contact with the skin. For more information, please refer to the Material Safety Data Sheet.

Storage

Under proper storage condition, QF3129M can be stored for up to 6 months. QF3129M is flammable. Keep away from all sources of heat, sparks, flame and sunlight.

Packaging

Available in 18kg/carboy.

Specification

Item	Result
State	Liquid
Colour	Brownish yellow
Specific Gravity @ 25°C	0.856 +/- 0.005
JIS Z 3197 8.2.2	
Non-volatile Solid Content (110°C, 1hr)	30.5 +/- 1.0 wt%
IPC-TM-650 2.3.34	
JIS Z 3197 8.1.3	
Halide Content	0.35 +/- 0.03 wt%
JIS Z 3197 8.1.4.2.1	
Acid Value Test	56.0 +/- 3 mg KOH/g flux
IPC-TM-650 2.3.13	
JIS Z 3197 8.1.4.1	
Water Extract Resistivity	> 1 x 10 ⁴ Ω-cm
JIS Z 3197 8.1.1	
Surface Insulation Resistance (85°C, 85%RH, 168hrs)	> 1 x 10 ⁸ Ω, Pass
IPC-TM-650 2.6.3.3	
JIS Z 3197 8.5.3	> 1 x 10 ¹¹ Ω, Pass
Electromigration (85°C, 88.5%RH, 596hrs)	Pass
IPC-TM-650 2.6.14.1	
Copper Corrosion Test	Pass
IPC-TM-650 2.6.15	
JIS Z 3197 8.4.1	
Copper Mirror Test	Classified as "H", Pass
IPC-TM-650 2.3.32	
JIS Z 3197 8.4.2	
Flux Activity Classification	ROH1
IPC J-STD-004	
Spread Factor	> 80% (V349)
JIS Z 3197 8.3.1.1	
Residue Dryness Test	Dry
IPC-TM-650 2.4.47	
JIS Z 3197 8.5.1	
Surface Finish	Matte

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